



## FEATURES

The RS3AB~RS3MB are available in SMB Package

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Fast reverse recovery time

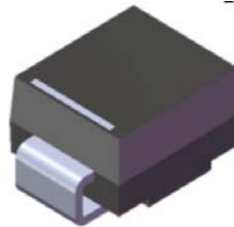
## ORDERING INFORMATION

Package Type	Part Number
SMB	RS3AB
	RS3BB
	RS3DB
	RS3GB
	RS3JB
	RS3KB
	RS3MB
SPQ	3,000pcs/Reel
AiT provides all RoHS Compliant Products	

## MECHANICAL DATA

- Case: SMB
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

## PIN DESCRIPTION



SMB



- 1 Cathode
- 2 Anode

**ABSOLUTE MAXIMUM RATINGS**

T<sub>A</sub> = 25°C, unless otherwise specified.

Parameter	Symbols	RS3AB	RS3BB	RS3DB	RS3GB	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3				A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I <sub>FSM</sub>	90				A
Maximum Forward Voltage at 3 A	V <sub>F</sub>	1.3				V
Maximum DC Reverse Current T <sub>A</sub> = 25 °C at Rated DC Blocking Voltage T <sub>A</sub> =125 °C	I <sub>R</sub>	5 100				μA
Typical Junction Capacitance at V <sub>R</sub> =4V, f=1MHz	C <sub>j</sub>	40				pF
Maximum Reverse Recovery Time*	t <sub>rr</sub>	150				ns
Typical Thermal Resistance**	R <sub>θJA</sub> R <sub>θJC</sub>	48 16				°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150				°C

\* Measured with I<sub>F</sub> = 0.5 A, I<sub>R</sub> = 1 A, I<sub>rr</sub> = 0.25 A

\*\* P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



T<sub>A</sub> = 25°C, unless otherwise specified.

Parameter	Symbols	RS3JB	RS3KB	RS3MB	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	600	800	1000	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3			A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I <sub>FSM</sub>	90			A
Maximum Forward Voltage at 3 A	V <sub>F</sub>	1.3			V
Maximum DC Reverse Current T <sub>A</sub> = 25 °C at Rated DC Blocking Voltage T <sub>A</sub> =125 °C	I <sub>R</sub>	5 100			μA
Typical Junction Capacitance at V <sub>R</sub> =4V, f=1MHz	C <sub>j</sub>	40			pF
Maximum Reverse Recovery Time*	t <sub>rr</sub>	250	500		ns
Typical Thermal Resistance**	R <sub>θJA</sub>	48			°C/W
	R <sub>θJC</sub>	16			
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150			°C

\* Measured with I<sub>F</sub> = 0.5 A, I<sub>R</sub> = 1 A, I<sub>rr</sub> = 0.25 A

\*\* P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

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### TYPICAL CHARACTERISTICS

Fig 1. Maximum Average Forward Current Rating

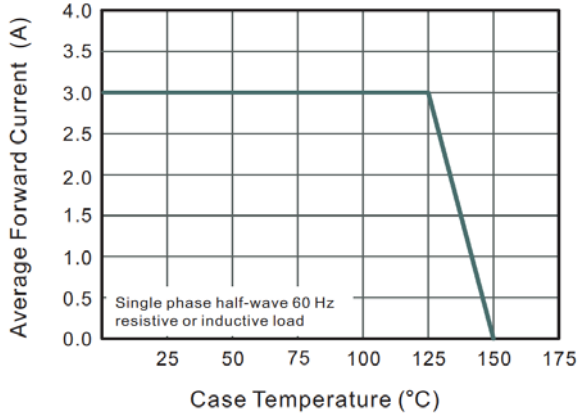


Fig 2. Typical Reverse Characteristics

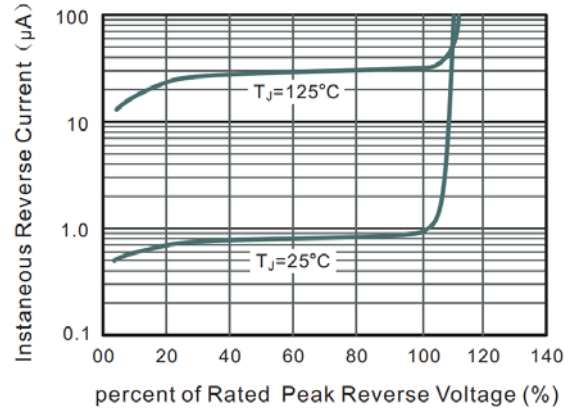


Fig 3. Typical Instantaneous Forward Characteristics

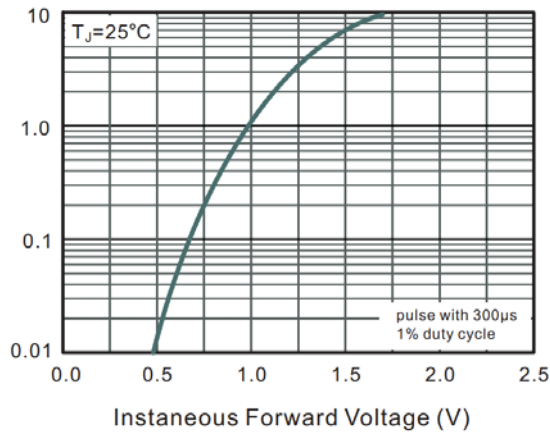


Fig 4. Typical Junction Capacitance

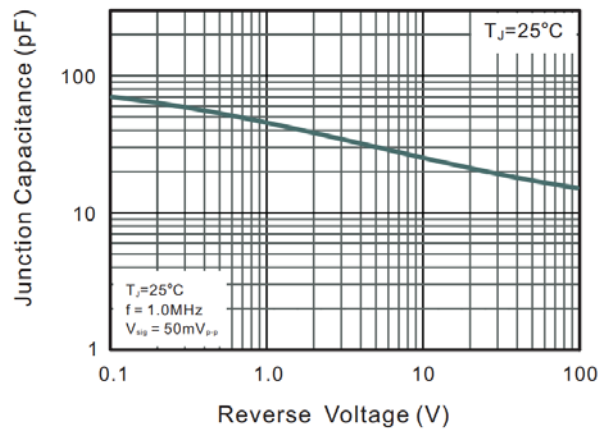
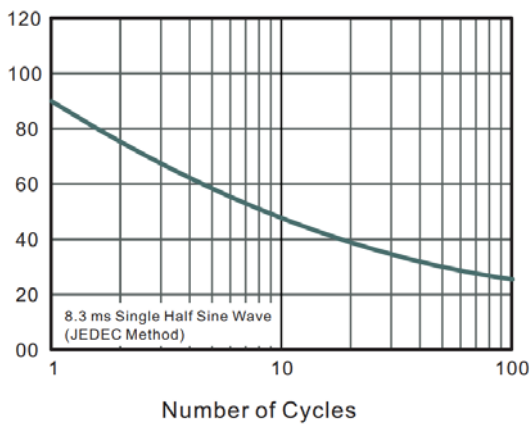


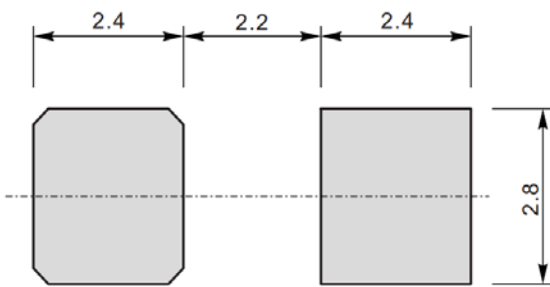
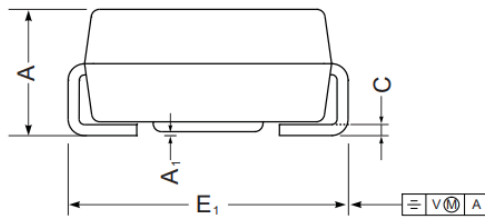
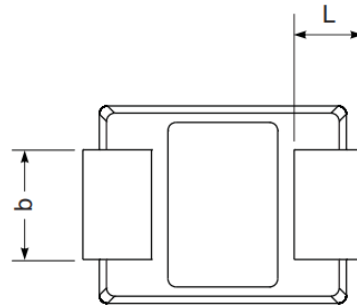
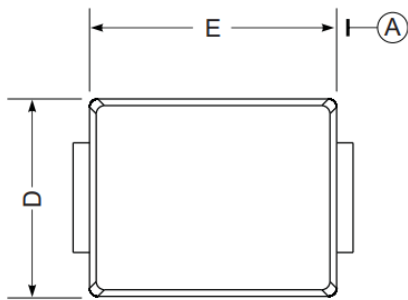
Fig 5. Maximum Non-Repetitive Peak Forward Surge Current





**PACKAGE INFORMATION**

Dimension in SMB (Unit: mm)



RECOMMENDED LAND PATTERN

Symbol	Min	Max
A	2.13	2.44
E	4.06	4.70
D	3.3	3.94
E <sub>1</sub>	5.08	5.59
A <sub>1</sub>	0.05	0.20
L	0.8	1.5
C	0.152	0.305
b	1.9	2.2



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